

## 10W 37.5-43.5GHz High Power Amplifier

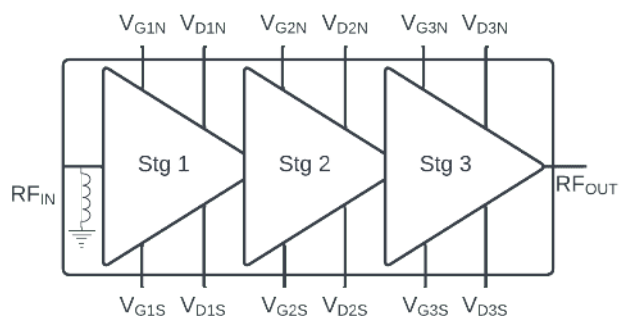
### GaN Monolithic Microwave IC

#### Description

The CHA8454-99F is a three stages High Power Amplifier operating between 37.5 and 43.5GHz and providing typically 10W of saturated output power and more than 24% of Power Added Efficiency. The typical power supply is 20V/540mA (quiescent current). Thanks to a low drain voltage biasing, the CHA8454-99F provides a junction temperature below 160°C, even in saturation.

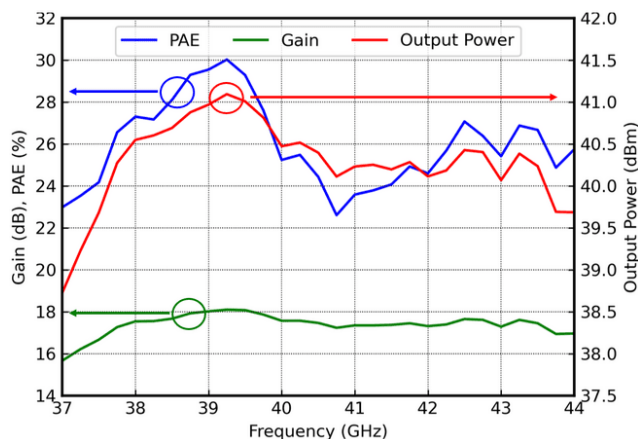
The circuit is manufactured on a space evaluated GaN-on-SiC HEMT process and is available in bare die form.

It is firstly dedicated to space, military and telecom applications and well suited for a wide range of microwave applications and systems.



#### Main Features

- Frequency range: 37.5 – 43.5GHz
- High output power: 10W
- High PAE > 24%
- Linear Gain: above 23dB
- DC bias: Vd=20V @Id=540mA
- Chip size: 3.6x2.9mm<sup>2</sup>
- Available in bare die



#### Main Electrical Characteristics

TB = +25°C (TB : Chip backside temperature)

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	37.5		43.5	GHz
Gain	Linear Gain		24		dB
Pout	Saturated Output Power		40.5		dBm
PAE	Power Added Efficiency		25		%

## Specifications

TB = +25°C, Vd = +20V, CW excitation

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	37.5		43.5	GHz
Gain	Linear Gain		24		dB
Pout	Saturated Output Power		40.5		dBm
PAE	Power Added Efficiency		25		%
Plin	Linear Power <sup>(1)</sup>		35.5		dBm
S11	Input Return Loss		-12		dB
S22	Output Return Loss		-8		dB
Idq	Quiescent Drain bias current		540		mA
Vd	Drain voltage		20		V

These values are representative of on-board measurements as defined on the drawing in paragraph "Recommended assembly plan".

<sup>(1)</sup> Linear Power defined at 19dBc Noise Power Ratio, 40MHz signal bandwidth, 10% notch

## Absolute Maximum Ratings <sup>(2)</sup>

TB = +25°C

Symbol	Parameter	Values	Unit
Vd	Drain bias voltage	27	V
Id	Drain current	3	A
Vg	Gate bias voltage	-7 to -1	V
Pin	Maximum Input Power	32	dBm

<sup>(2)</sup> Operation of this device above any one of these parameters may cause permanent damage.

## Recommended Operating Range <sup>(3), (4)</sup>

Symbol	Parameter	Values	Unit
Vd	Drain bias voltage	18 to 25	V
Id	Drain bias current	100 to 540	mA
Vg	Gate bias voltage	-5 to -2.5	V
Tj	Maximum Junction temperature <sup>(5)</sup>	200	°C

<sup>(3)</sup> Electrical performances are defined for specified test conditions

<sup>(4)</sup> Electrical performances are not guaranteed over all recommended operating conditions

<sup>(5)</sup> See Device thermal performances section

## Temperature Range

TB	Operating temperature range at MMIC backside level	-40 to +95	°C
T <sub>stg</sub>	Storage temperature range	-55 to +150	°C

**Typical Bias Conditions****TB=+25°C**

Symbol	Pad N°	Parameter	Values	Unit
Vg	3, 5, 7, 25, 27, 29	Gate voltage tuned for Idq~560mA	-3.1	V
Vd	9, 11, 13, 19, 21, 23	Drain Voltage	20	V

**“Power ON” sequence**

1. Bias HPA gate voltage at Vg close to Vpinch-off (Vg~-5V)
2. Set Vd bias voltage to 0V: Id=0mA
3. Apply Vd bias voltage, Vd = 20V: Id=0mA
4. Increase Vg up to quiescent bias drain current Idq=540mA
5. Apply RF input Power

**“Power OFF” sequence**

1. Turn off RF input power
2. Bias HPA Gate voltage at Vg~-5V: Id=0mA
3. Decrease Vd bias voltage down to 0V
4. Turn Vg bias voltage to 0V

## Device thermal performance

All the figures given in this section are obtained assuming that the device is only cooled down by conduction through the thermal pad (no convection mode considered).

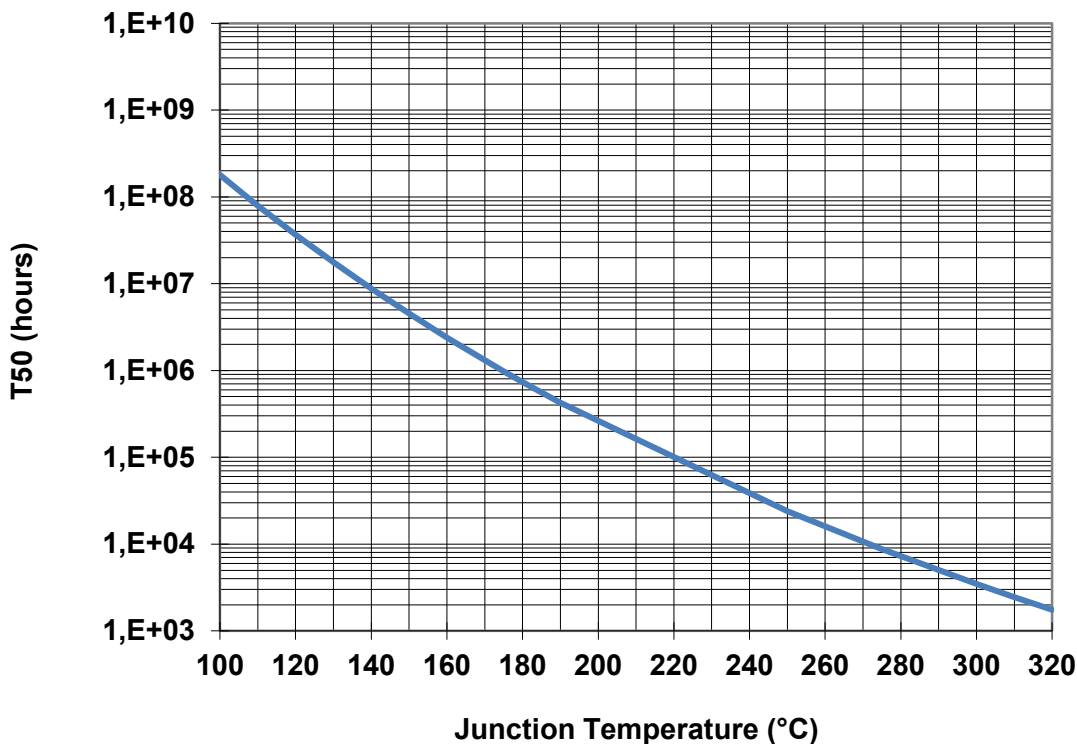
The temperature is monitored at the chip back-side interface (TB).

For nominal operating, the system maximum temperature must be adjusted in order to guarantee that the Junction Temperature remains below the maximum value specified in the Recommended Operating Ratings table.

Therefore, the system PCB must be designed to comply with this requirement.

Thermal Resistance <sup>(1)</sup>	$R_{th\_eq}$	Pin at max PAE TB = 85°C, Vd = 20V, Idq = 560 mA, Pin = 26 dBm, Freq = 40GHz, Pdis = 32 W	1.99	°C/W
Junction Temperature	$T_j$		147	°C
Median Life	T50		4E6	Hrs
Thermal Resistance <sup>(1)</sup>	$R_{th\_eq}$	Pin at max PAE + 4dB TB = 85°C, Vd = 20V, Idq = 560 mA, Pin = 30 dBm, Freq = 40GHz, Pdis = 39 W	2.61	°C/W
Junction Temperature	$T_j$		186	°C
Median Life	T50		4E5	Hrs

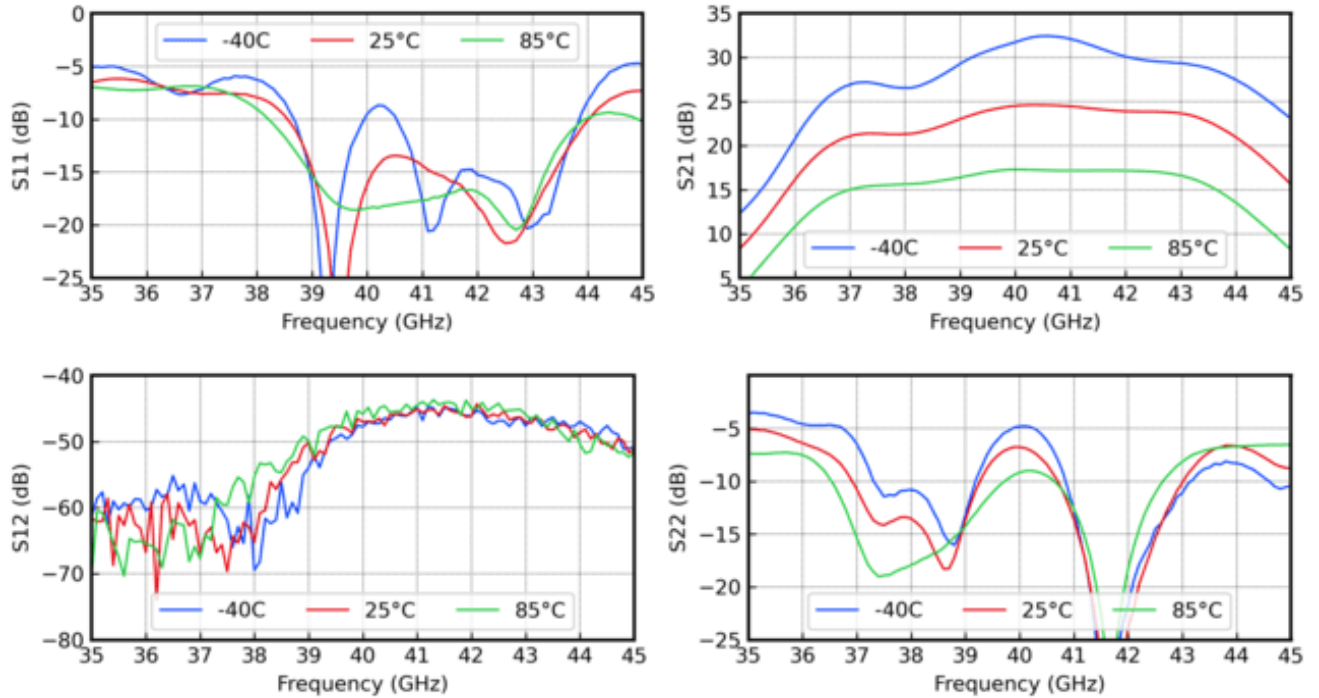
<sup>(1)</sup> Thermal resistance measured at the backside of the chip



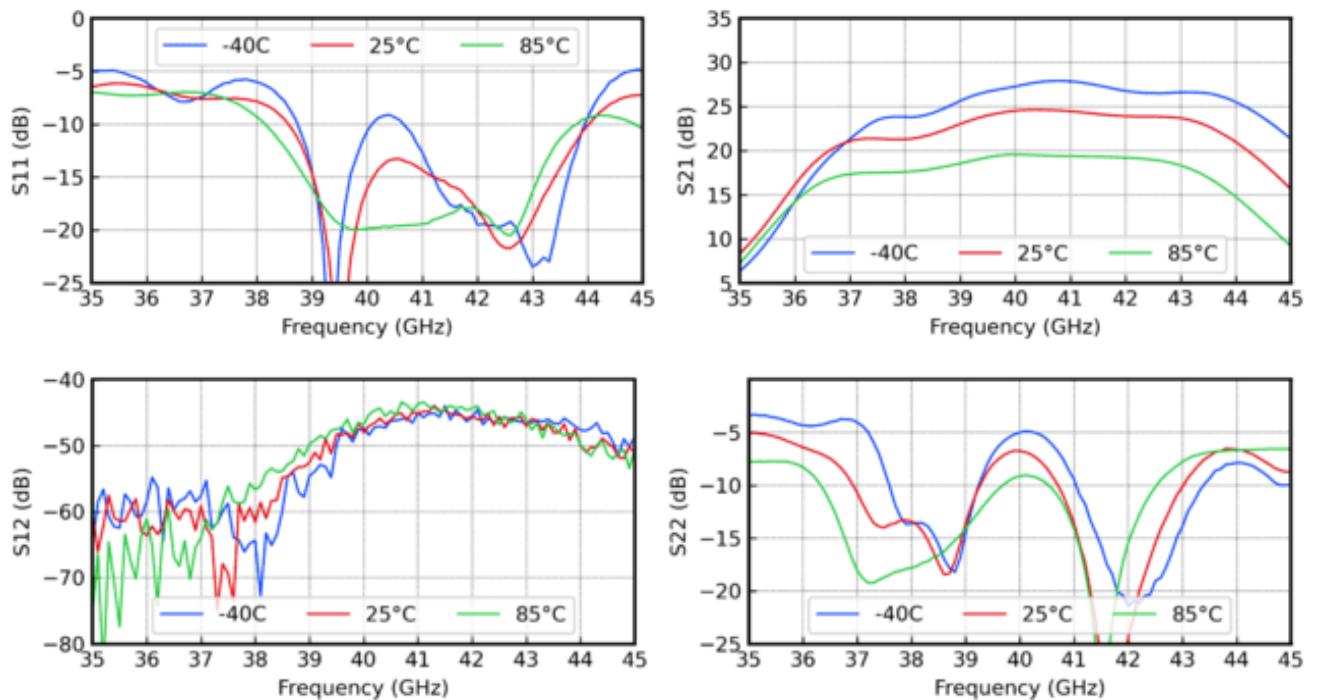
**Typical Board Measurements : Small Signal Performance**

Measurements reference is at the connector plane for S11 and S22, and de-embedded at the wire-bondings planes of the RF lines for S21 and S12.

**S Parameters versus frequency and temperature**  
 Test conditions :  $V_D = 20V$ ,  $I_{dq} = 560mA$ , TB = -40°C / 25°C / 85°C



**S Parameters versus frequency and temperature**  
 Test conditions :  $V_D = 20V$ , VG fixed at  $I_{dq} = 560mA$  at 25°C TB, TB = -40°C / 25°C / 85°C

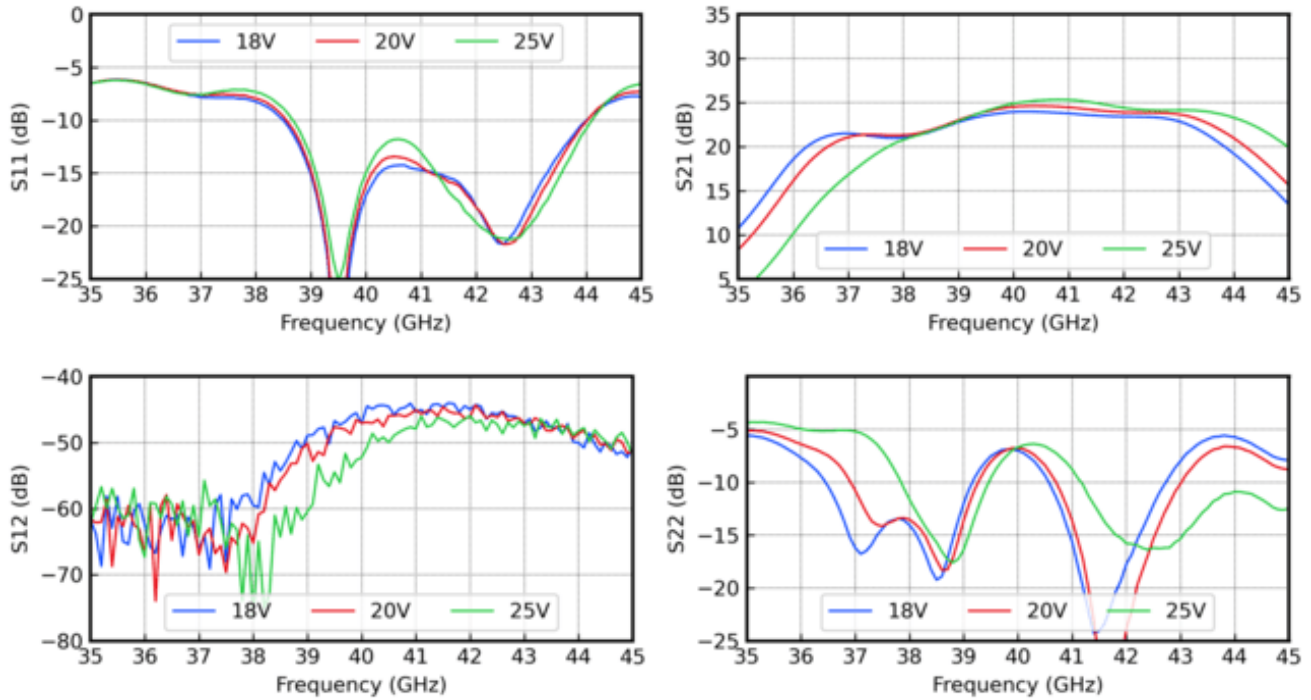


## Typical Board Measurements : Small Signal Performance

Measurements reference is at the connector plane for S11 and S22, and de-embedded at the wire-bondings planes of the RF lines for S21 and S12.

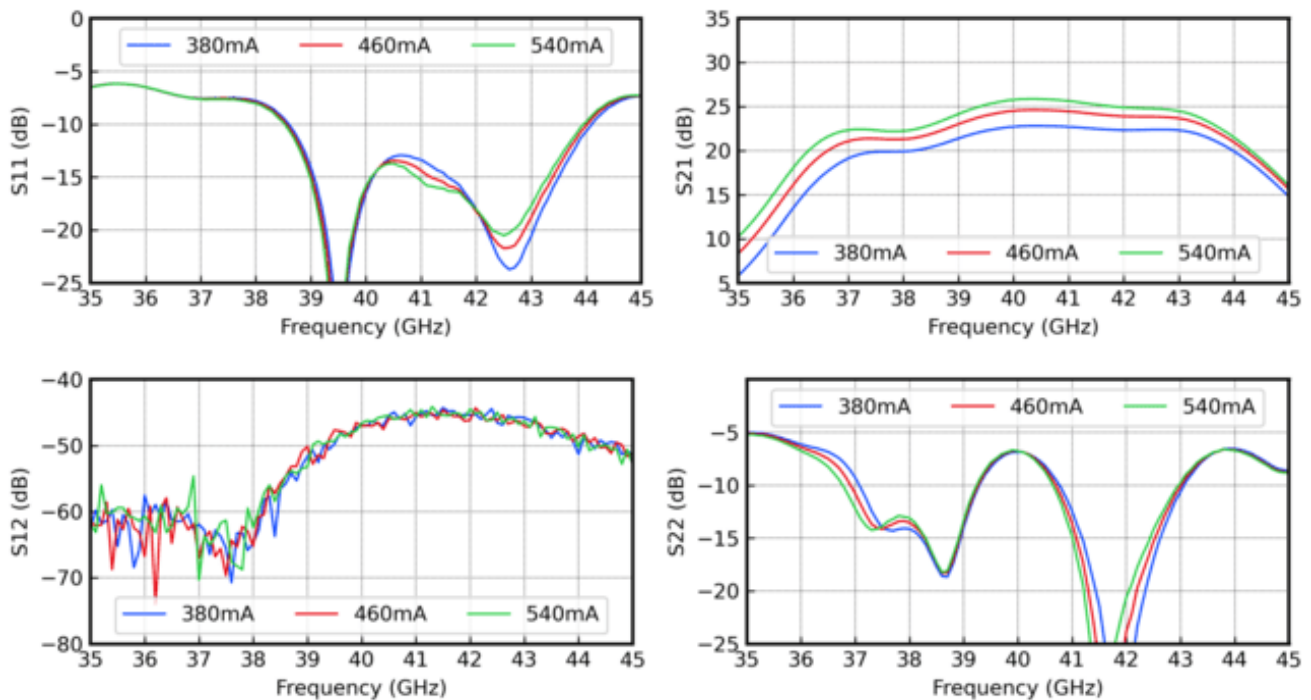
### S Parameters versus frequency and Drain Voltage

Test conditions :  $I_{dq} = 560\text{mA}$ ,  $T_B = 25^\circ\text{C}$



### S Parameters versus frequency and Quiescent Drain Current

Test conditions :  $V_D = 20\text{V}$ ,  $T_B = 25^\circ\text{C}$



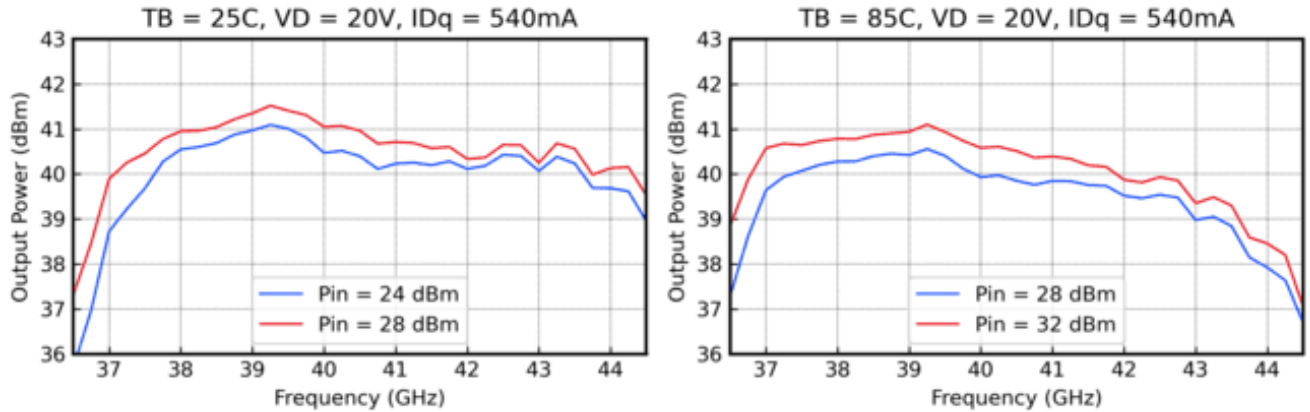
**Typical Board Measurements : Large Signal Performance**

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

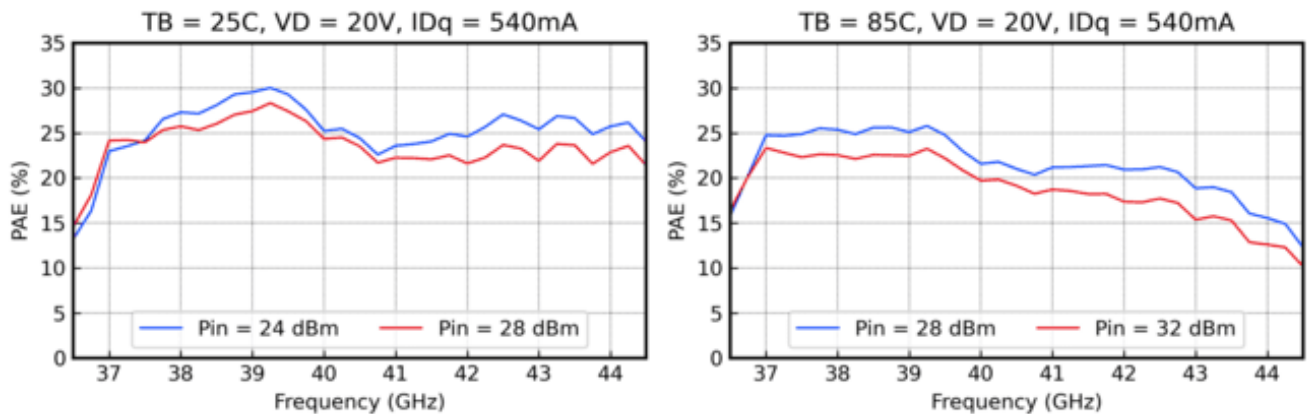
**Performance versus frequency and temperature**

Test conditions :  $V_D = 20V$ ,  $I_{dq} = 540mA$ ,  $TB = 25^\circ C / 85^\circ C$

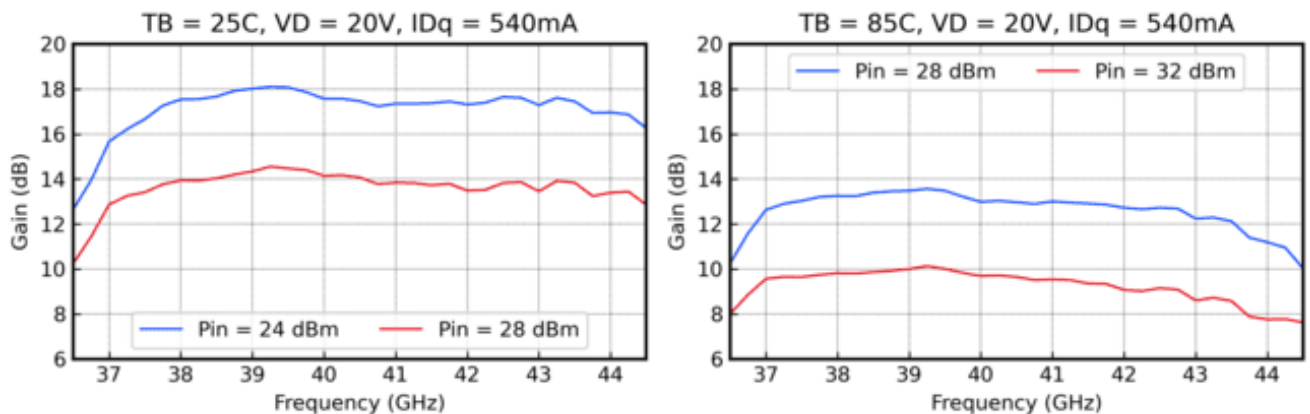
**Output Power versus Frequency and Input Power**



**Power Added Efficiency versus Frequency and Input Power**



**Gain versus Frequency and Input Power**



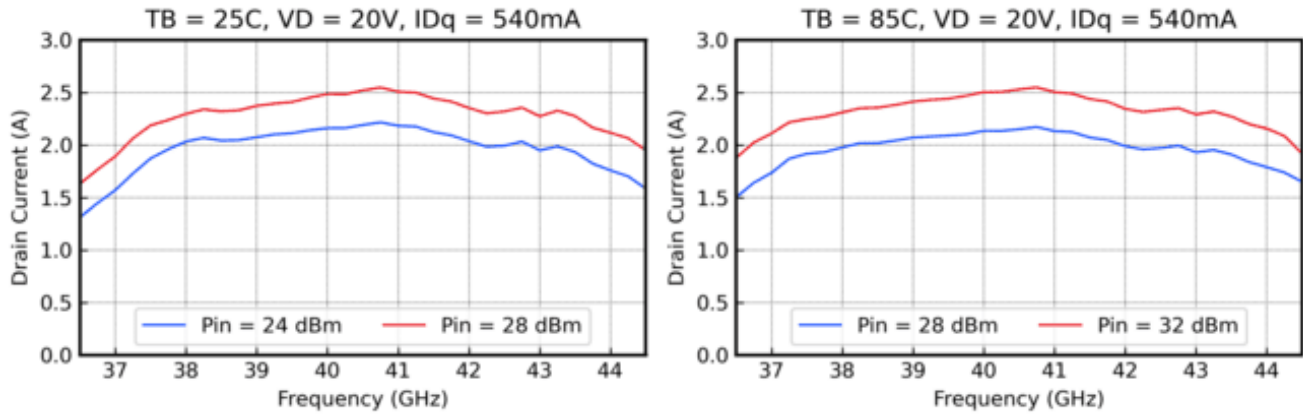
## Typical Board Measurements : Large Signal Performance

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

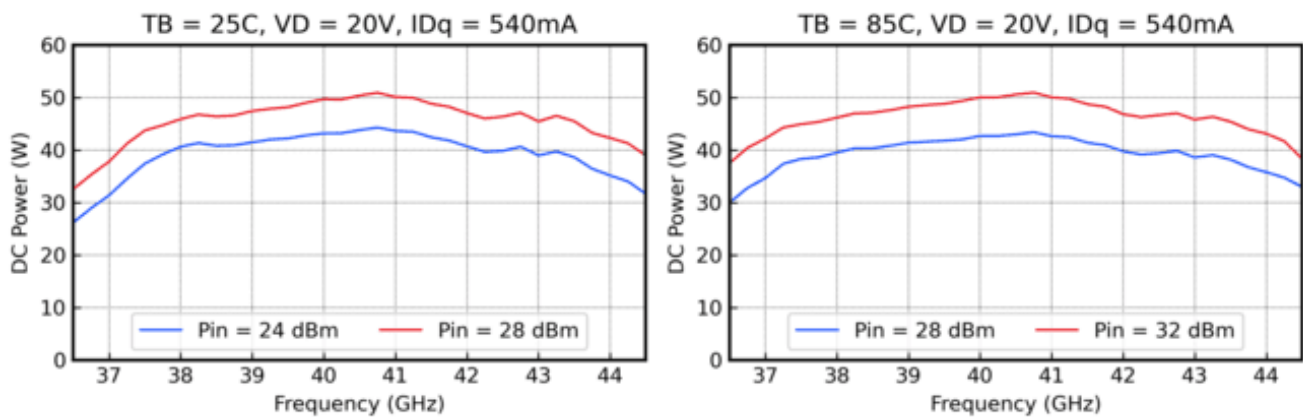
### Performance versus frequency and temperature

Test conditions :  $V_D = 20V$ ,  $I_{dq} = 540mA$ ,  $TB = 25^\circ C / 85^\circ C$ ,  $P_{in}$  chosen at max PAE and  $P_{sat}$

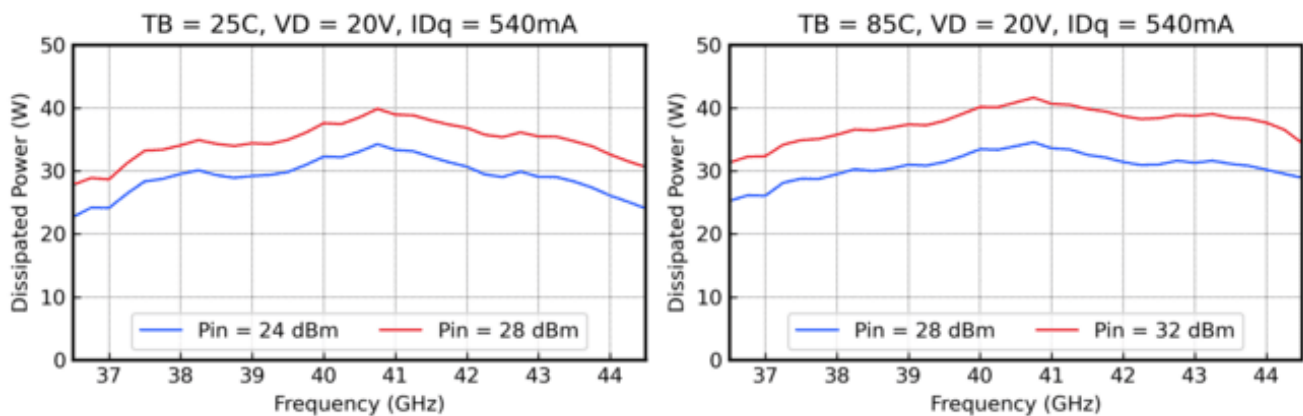
### Drain Current versus Frequency and Input Power



### DC Power Consumption versus Frequency and Input Power



### Dissipated Power versus Frequency and Input Power



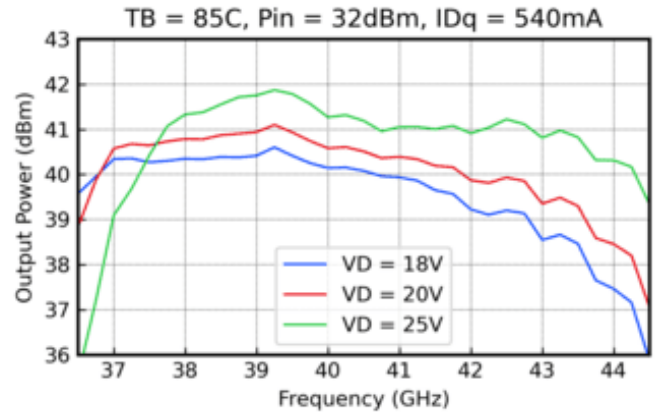
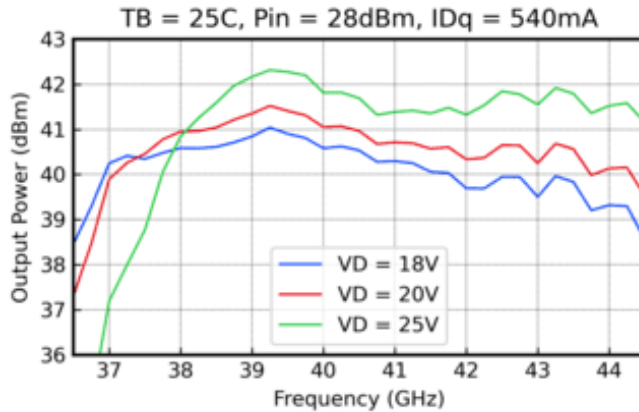
**Typical Board Measurements : Large Signal Performance**

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

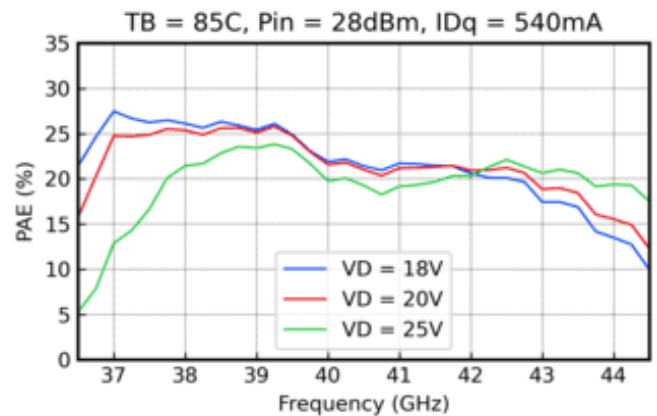
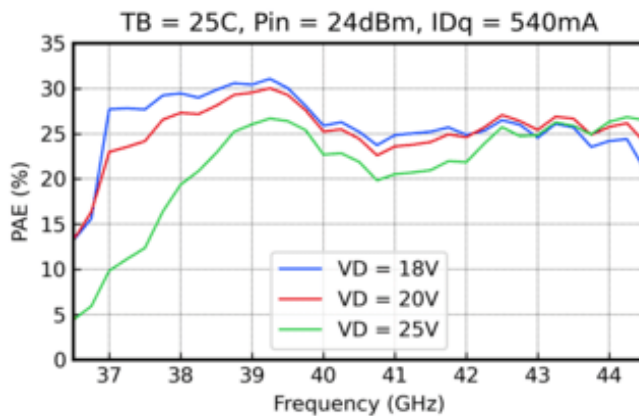
**Performance versus frequency and temperature**

Test conditions :  $I_{dq} = 540\text{mA}$ ,  $TB = 25^\circ\text{C} / 85^\circ\text{C}$

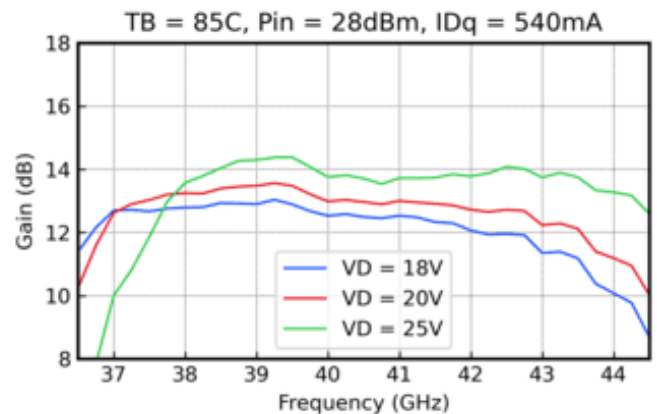
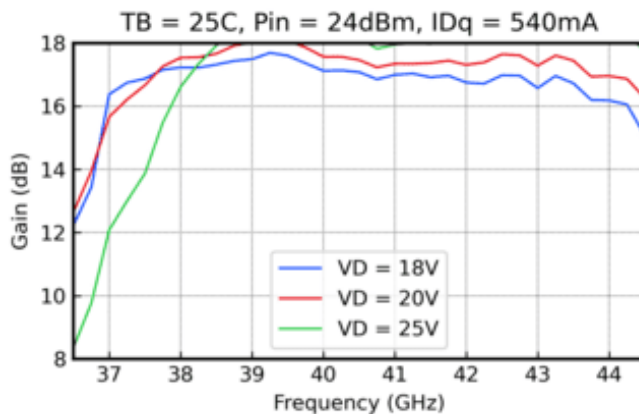
**Output Power versus Frequency and Drain Voltage, Pin at Psat**



**Power Added Efficiency versus Frequency and Drain Voltage, Pin at max PAE**



**Gain versus Frequency and Drain Voltage, Pin at max PAE**



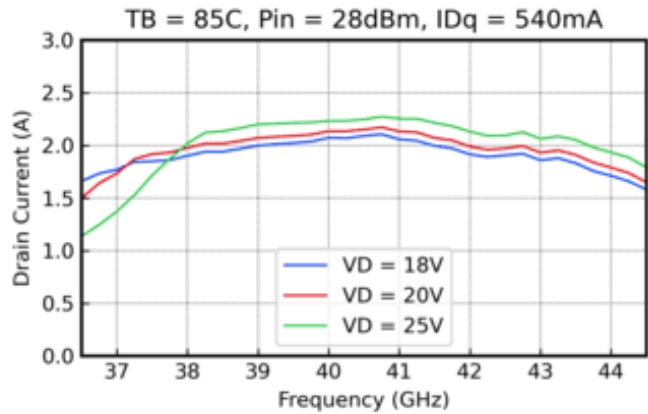
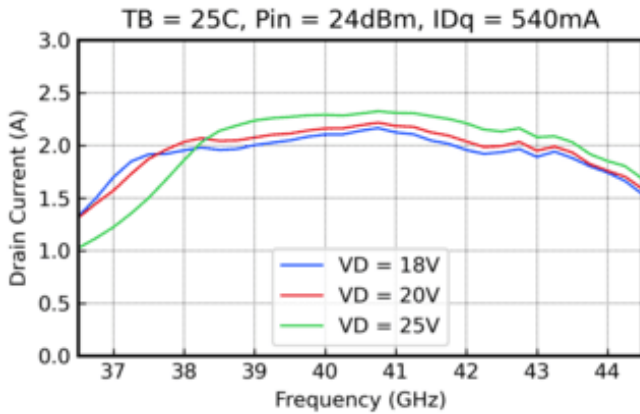
## Typical Board Measurements : Large Signal Performance

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

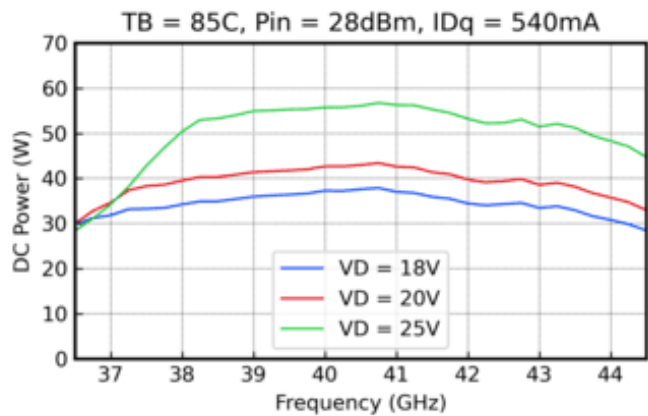
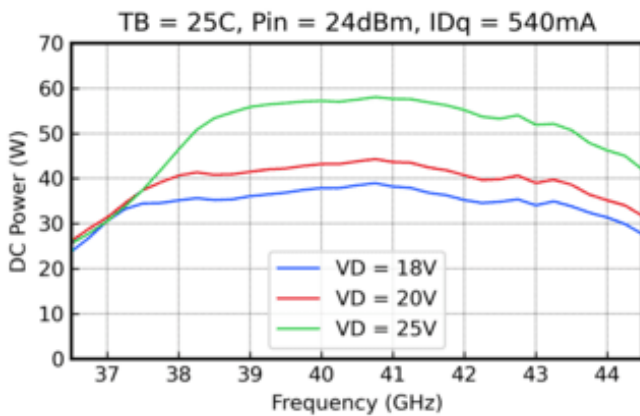
### Performance versus frequency and temperature

Test conditions :  $I_{dq} = 540\text{mA}$ ,  $T_B = 25^\circ\text{C} / 85^\circ\text{C}$

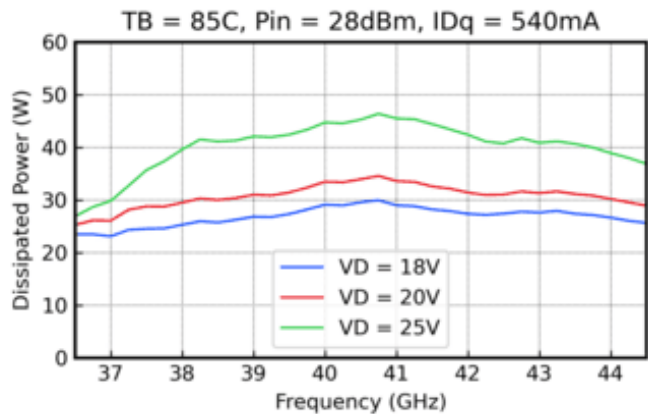
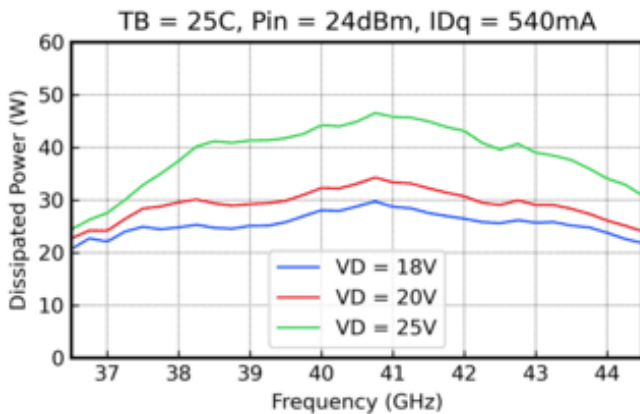
#### Drain Current versus Frequency and Drain Voltage, Pin at max PAE



#### DC Power Consumption versus Frequency and Drain Voltage, Pin at max PAE



#### Dissipated Power versus Frequency and Drain Voltage, Pin at max PAE



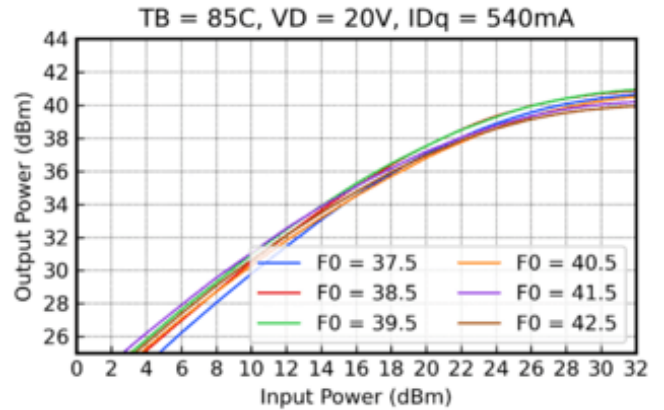
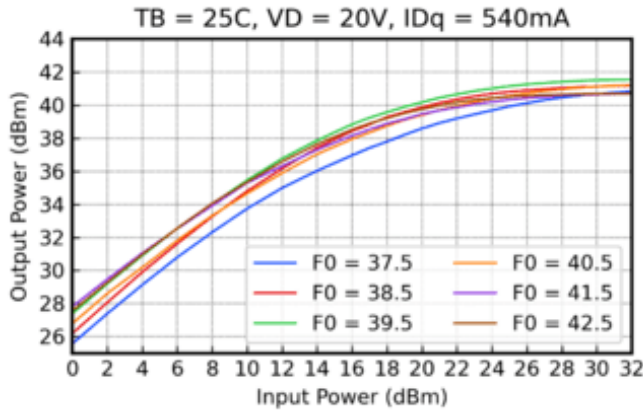
**Typical Board Measurements : Large Signal Performance**

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

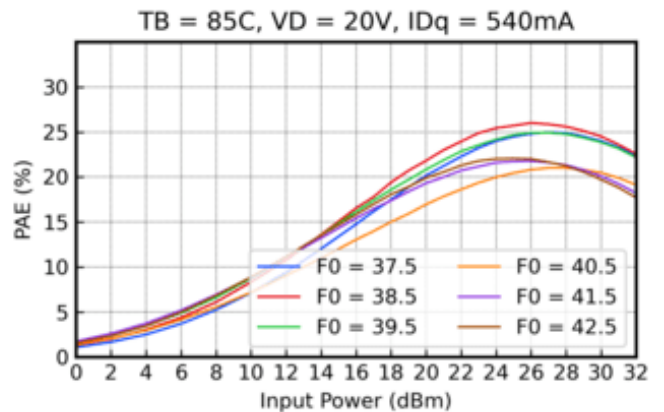
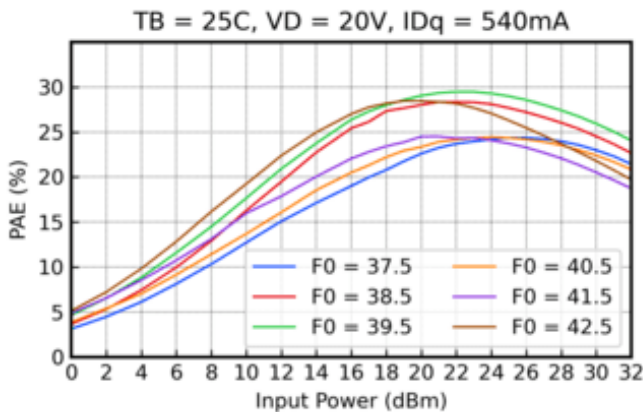
**Performance versus frequency and temperature**

Test conditions :  $I_{dq} = 540\text{mA}$ ,  $TB = 25^\circ\text{C} / 85^\circ\text{C}$

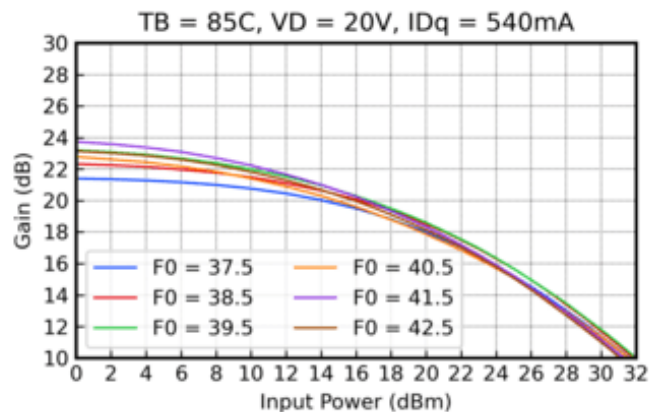
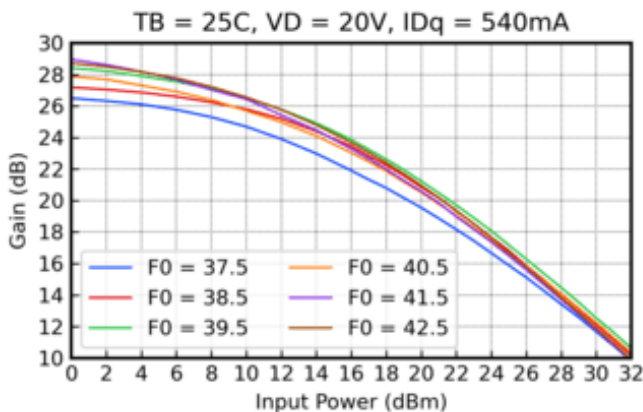
**Output Power versus Input Power and Frequency**



**Power Added Efficiency versus Input Power and Frequency**



**Gain versus Input Power and Frequency**



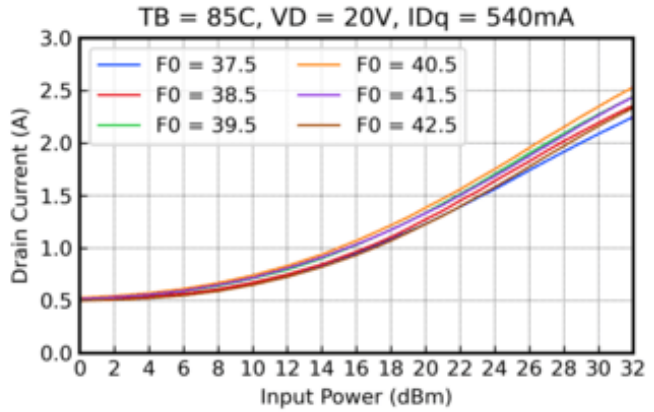
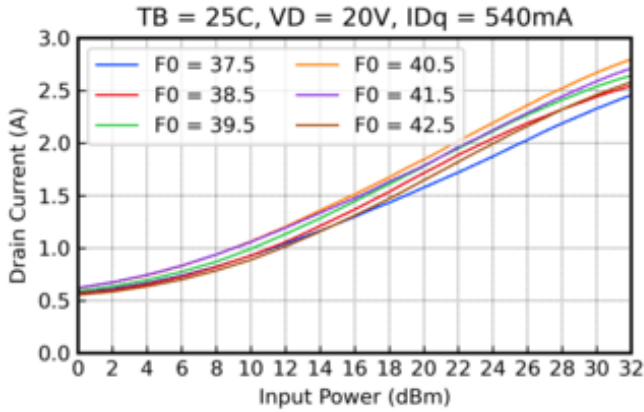
## Typical Board Measurements : Large Signal Performance

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

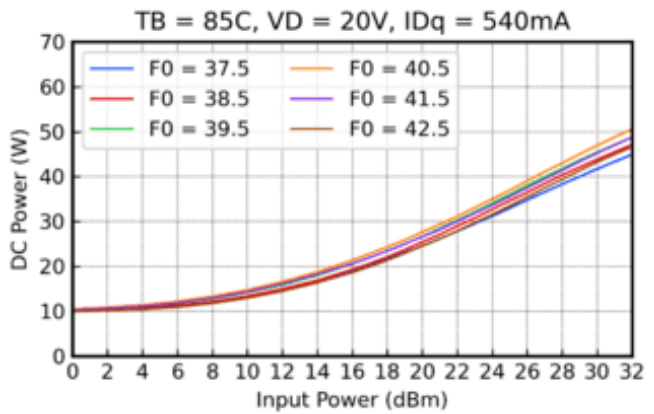
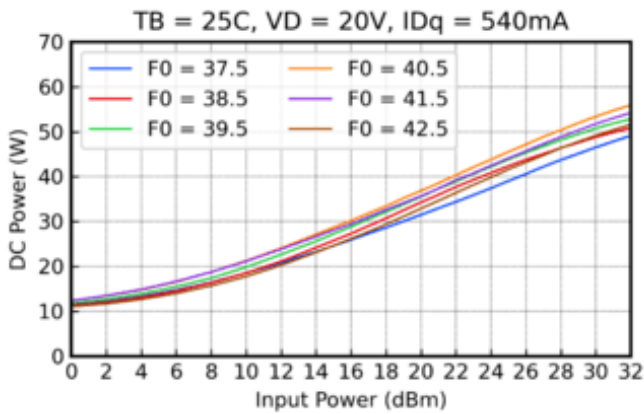
### Performance versus frequency and temperature

Test conditions :  $I_{dq} = 540\text{mA}$ ,  $T_B = 25^\circ\text{C} / 85^\circ\text{C}$

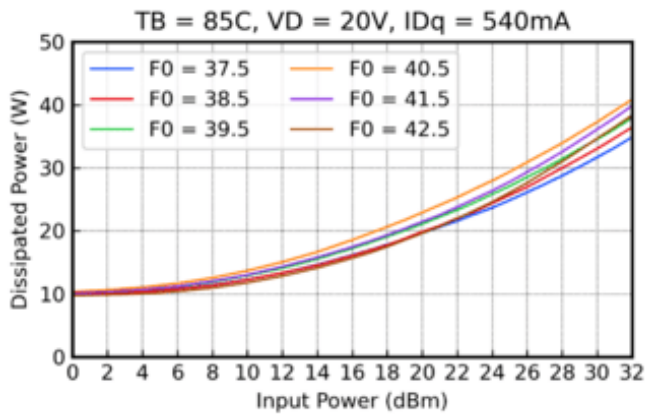
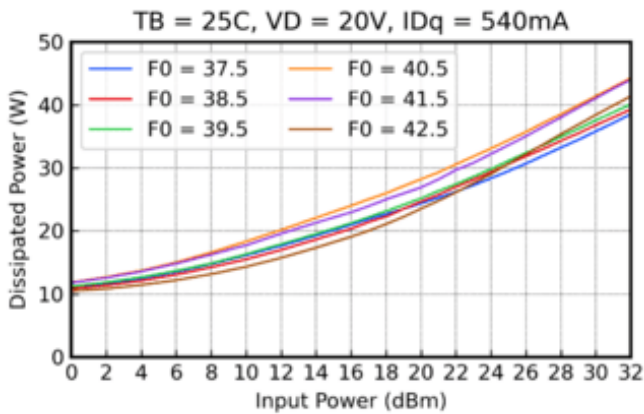
#### Drain Current versus Input Power and Frequency



#### DC Power Consumption versus Input Power and Frequency



#### Dissipated Power versus Input Power and Frequency



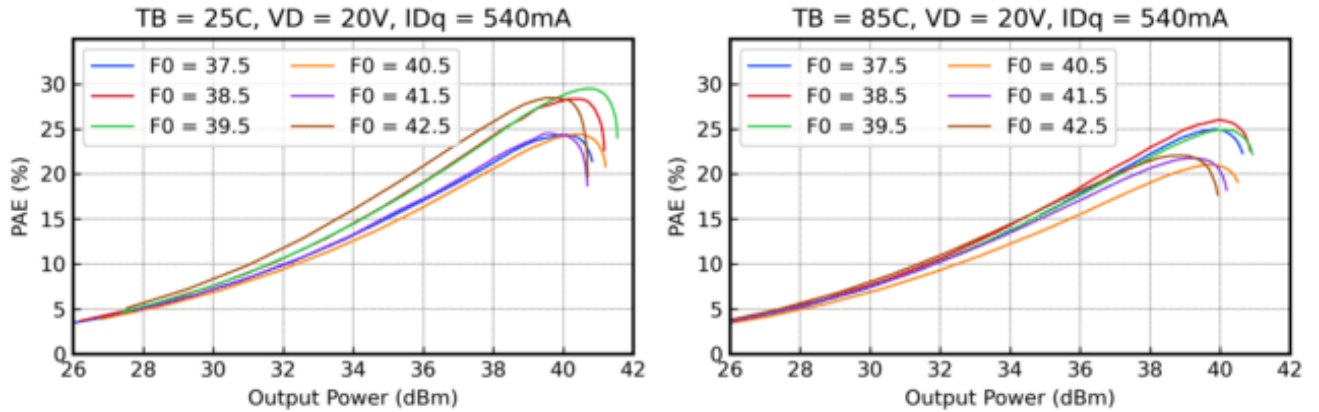
**Typical Board Measurements : Large Signal Performance**

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

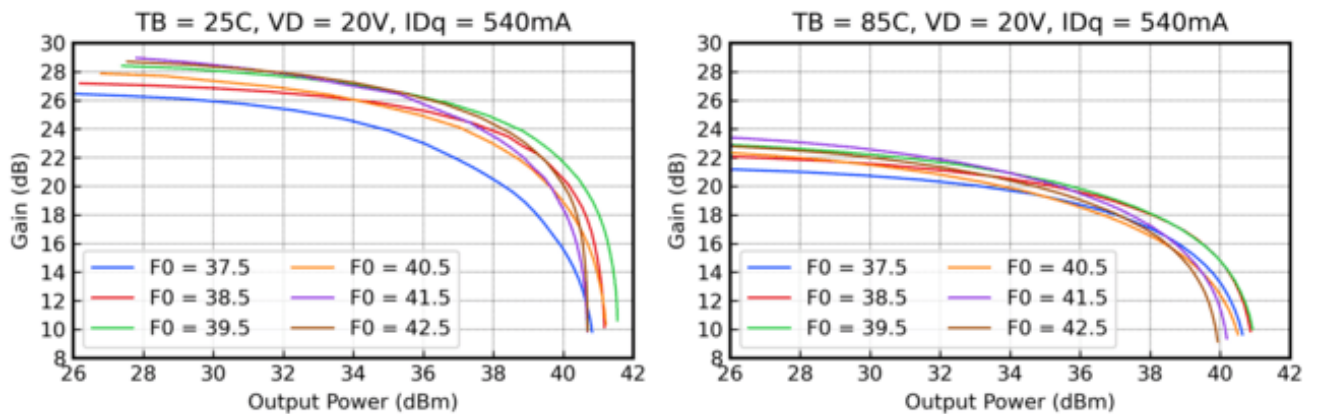
**Performance versus frequency and temperature**

Test conditions :  $I_{dq} = 540\text{mA}$ ,  $TB = 25^\circ\text{C} / 85^\circ\text{C}$

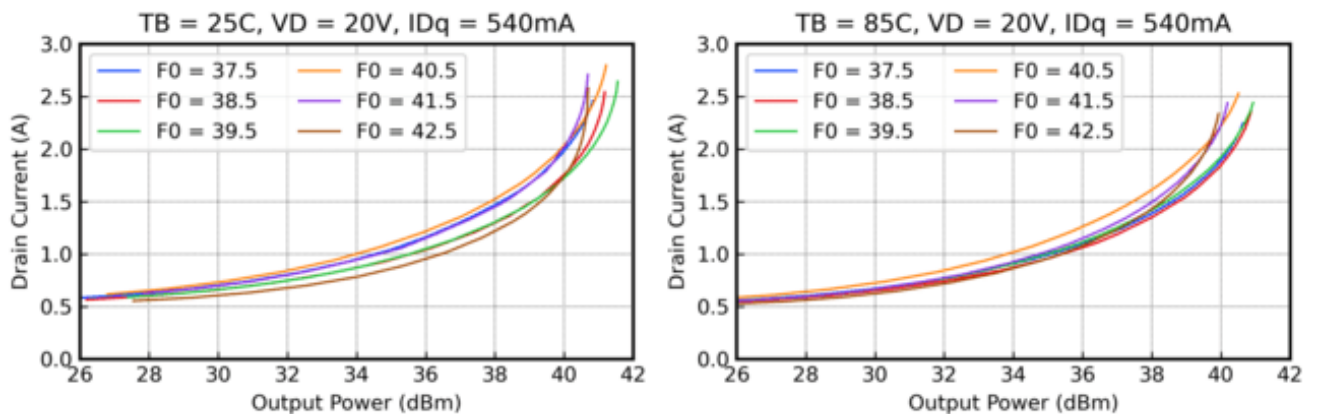
**Power Added Efficiency versus Output Power and Frequency**



**Gain versus Output Power and Frequency**



**Drain Current versus Output Power and Frequency**



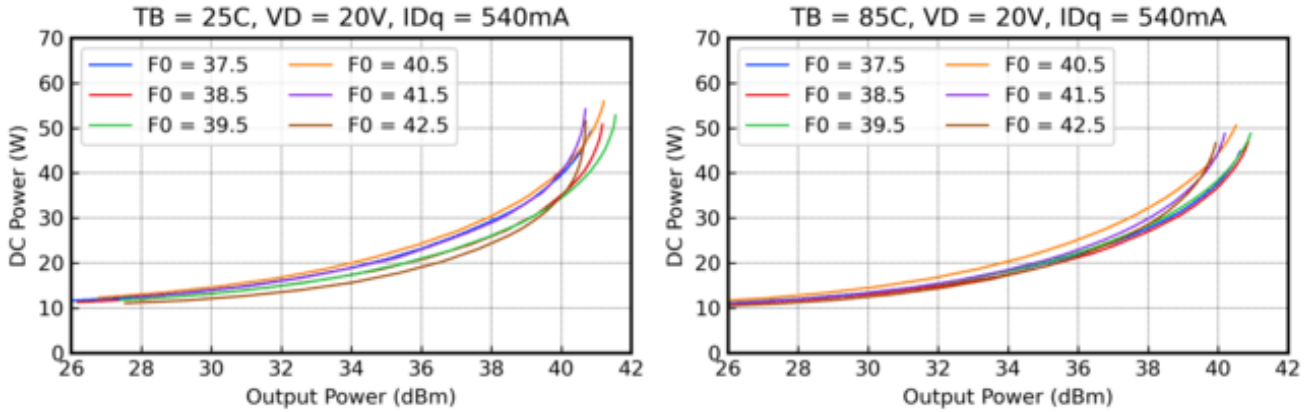
## Typical Board Measurements : Large Signal Performance

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

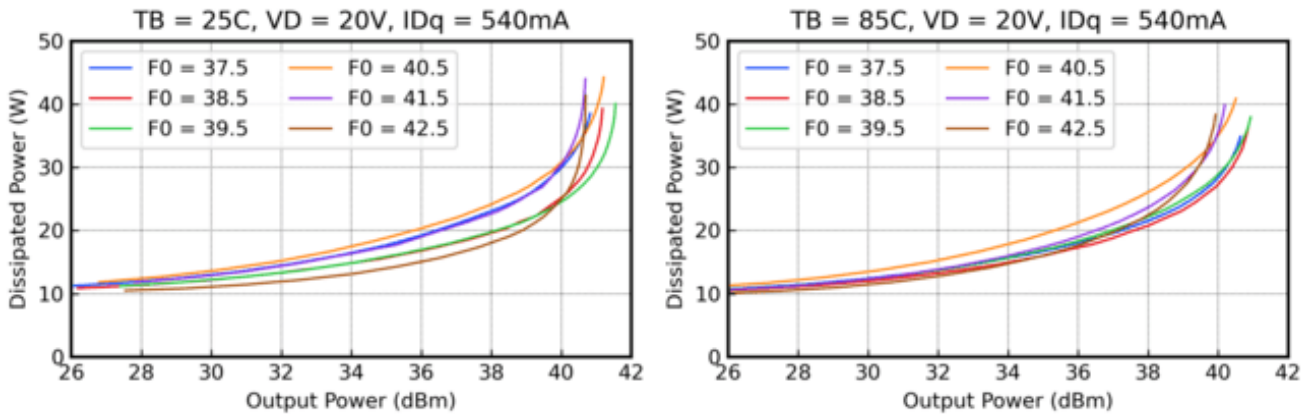
### Performance versus frequency and temperature

Test conditions :  $V_D = 20V$ ,  $I_{dq} = 540mA$ ,  $T_B = 25^\circ C / 85^\circ C$

#### DC Power Consumption versus Output Power and Frequency



#### Dissipated Power versus Output Power and Frequency

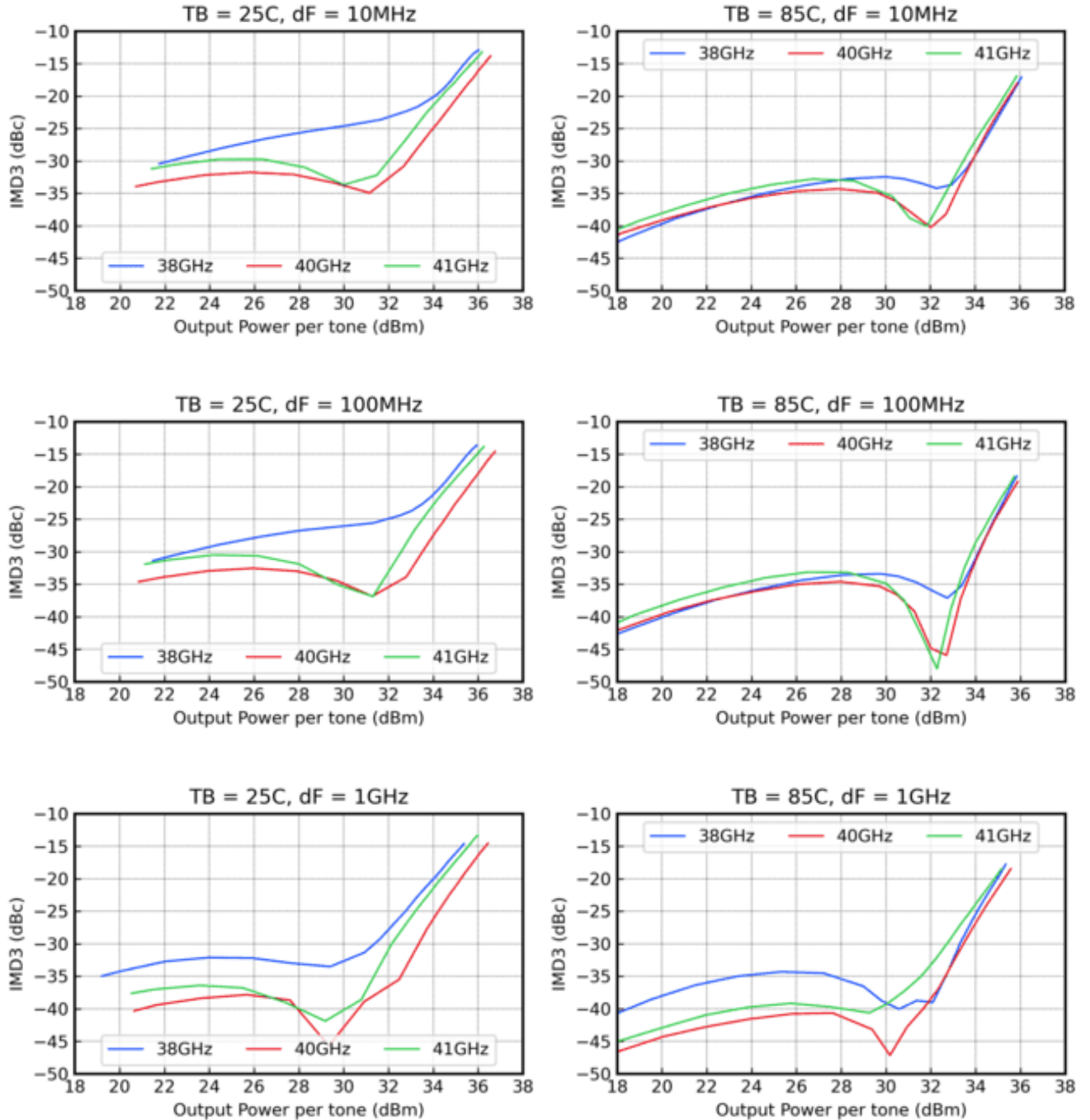


**Typical Board Measurements : Two Tone Large Signal Performance**

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

**IMD3 versus Output Power and Central Frequency**

Test conditions : VD = 20V, TB = 25°C & IDq = 230mA, TB = 85°C & IDq = 310mA

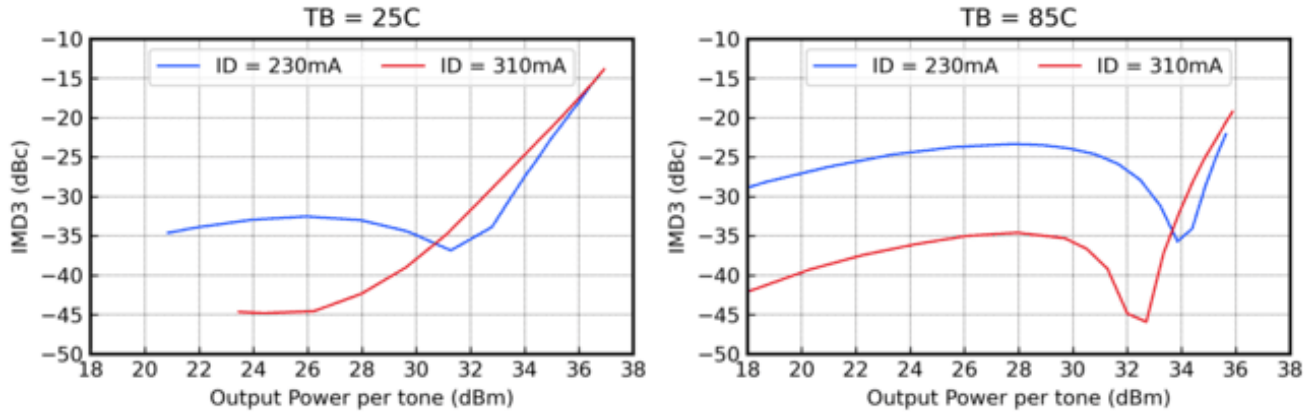


## Typical Board Measurements : Two Tone Large Signal Performance

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

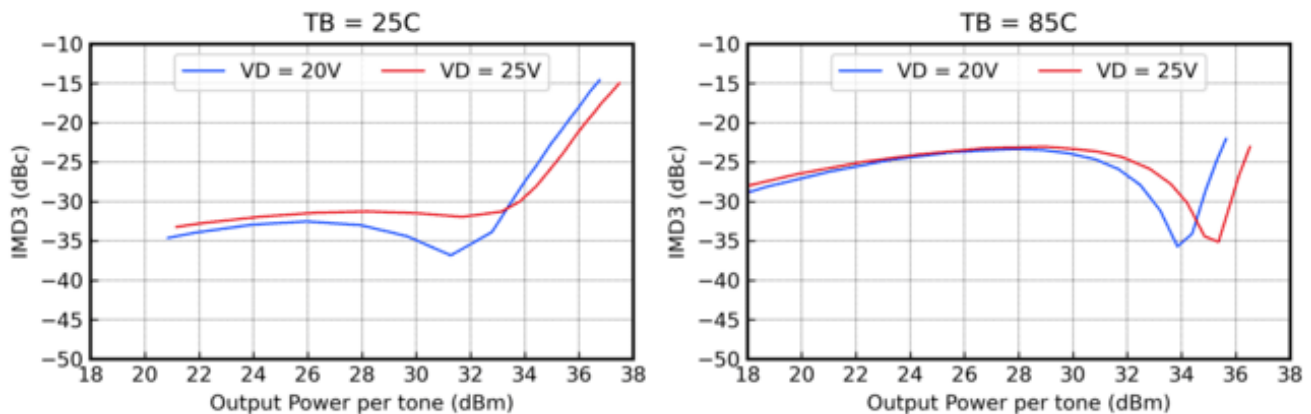
### IMD3 versus Output Power and Quiescent Current

Test conditions : F0 = 40GHz, VD = 20V, TB = 25°/85°C, Tone spacing : 100MHz



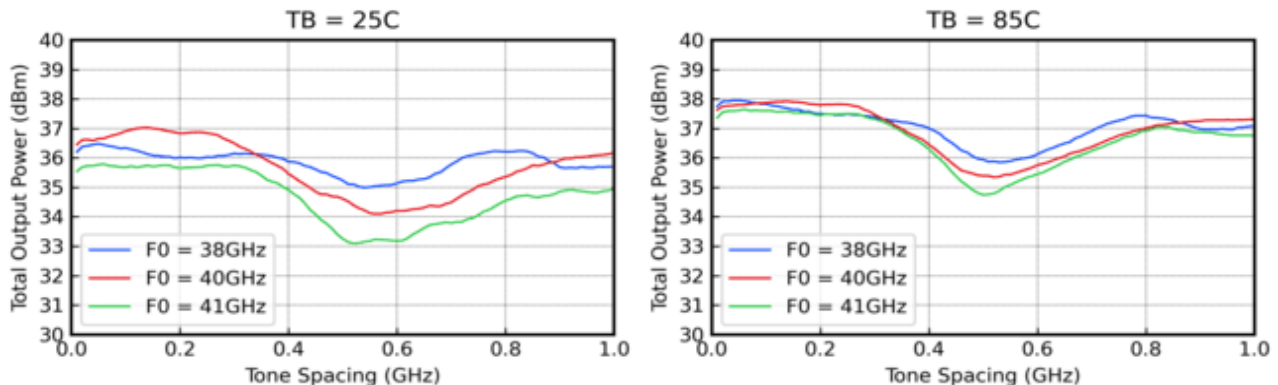
### IMD3 versus Output Power and Drain Voltage

Test conditions : F0 = 40GHz, IDq = 230mA, TB = 25°/85°C, Tone spacing : 100MHz



### Total Output Power at -23dBc IMD3 versus Tone Spacing and Central Frequency

Test conditions : VD = 20V, IDq = 230mA, TB = 25°/85°C, IMD3 = -23dBc

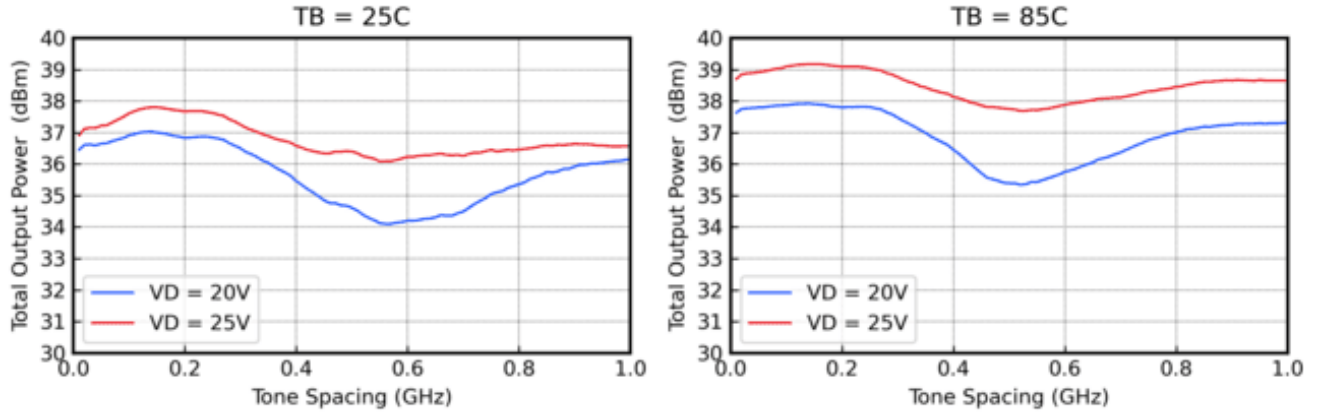


**Typical Board Measurements : Two Tone Large Signal Performance**

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

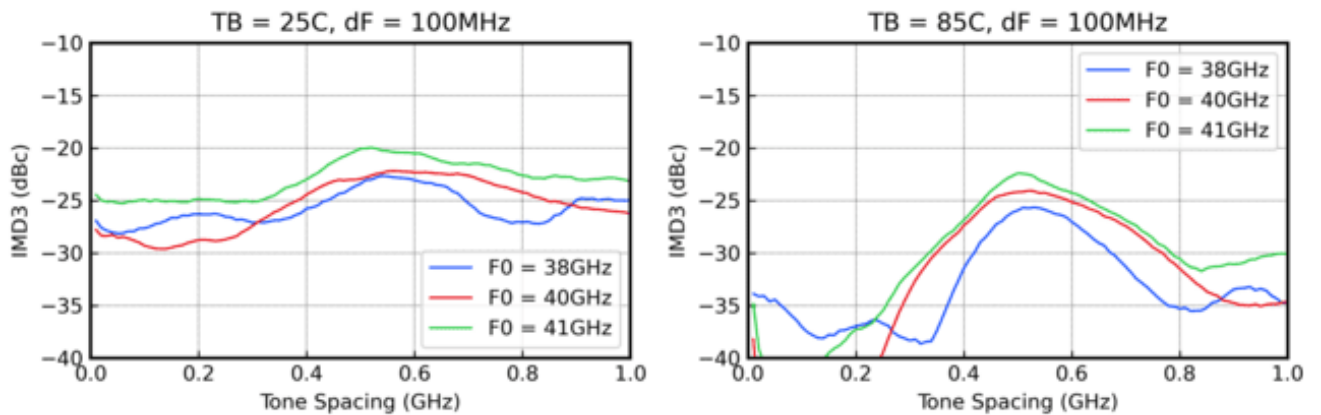
**Total Output Power at -23dBc IMD3 versus Tone Spacing and Drain Voltage**

Test conditions : F0 = 40GHz, I<sub>dq</sub> = 230mA, TB = 25°/85°C, IMD3 = -23dBc



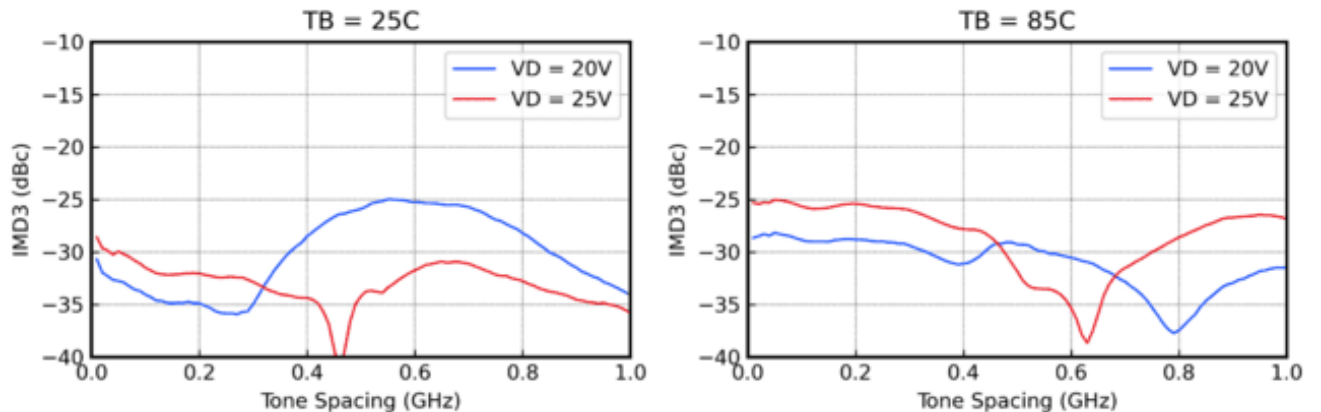
**IMD3 at 36dBm Total Output Power, versus Tone Spacing and Central Frequency**

Test conditions : I<sub>dq</sub> = 230mA, VD = 20V, TB = 25°/85°C



**IMD3 at 36dBm Total Output Power, versus Tone Spacing and Drain Voltage**

Test conditions : F0 = 40GHz, I<sub>dq</sub> = 230mA, TB = 25°/85°C



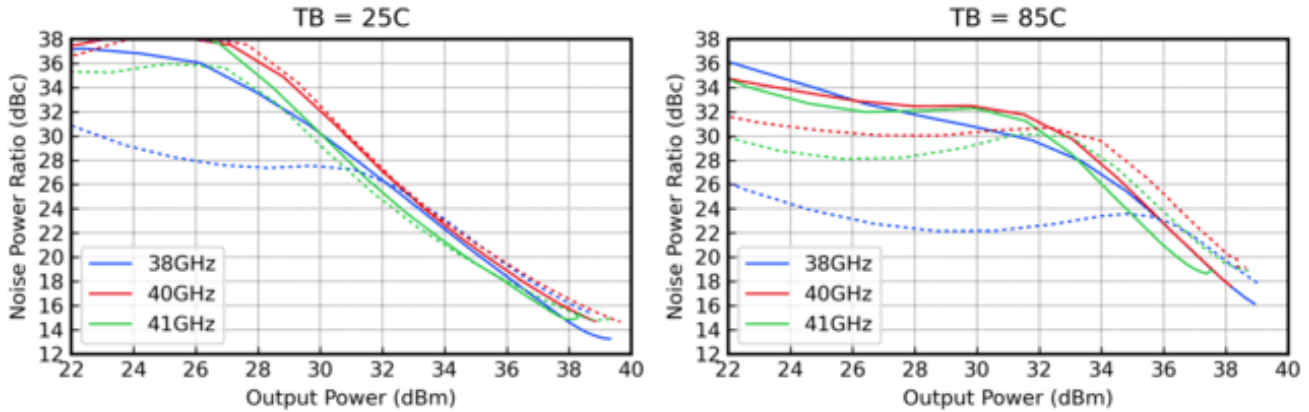
## Typical Board Measurements : Noise Power Ratio

**NPR Signal : 40MHz Signal Bandwidth, 10% Notch**

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

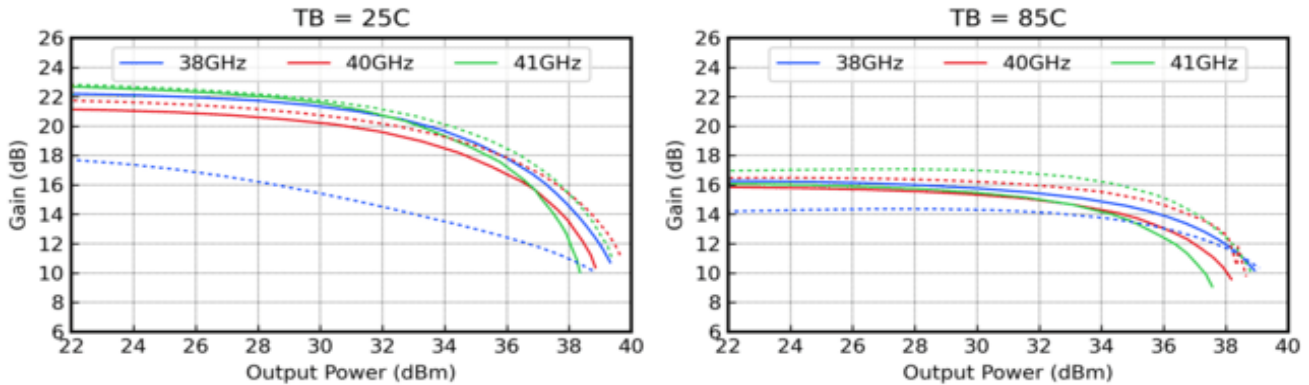
### NPR versus Output Power and Central Frequency

**Test conditions :**  $I_{dq} = 310\text{mA}$ , TB = 25°/85°C, solid line VD = 20V, dashed line VD = 25V



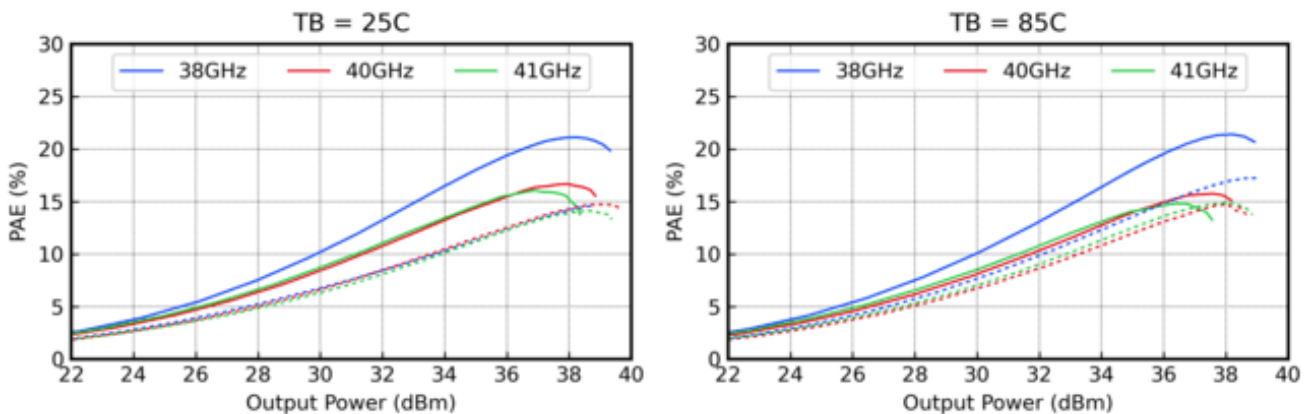
### Gain versus Output Power and Central Frequency

**Test conditions :**  $I_{dq} = 310\text{mA}$ , TB = 25°/85°C, solid line VD = 20V, dashed line VD = 25V



### PAE versus Output Power and Central Frequency

**Test conditions :**  $I_{dq} = 310\text{mA}$ , TB = 25°/85°C, solid line VD = 20V, dashed line VD = 25V



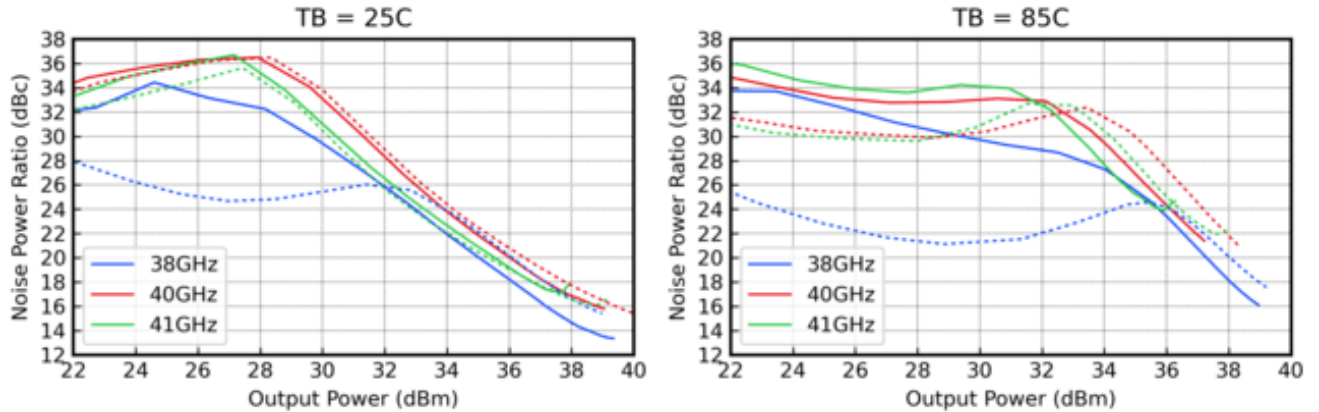
**Typical Board Measurements : Noise Power Ratio**

**NPR Signal : 1GHz Signal Bandwidth, 10% Notch**

Measurements reference plane is de-embedded at the wire-bondings planes of the RF lines.

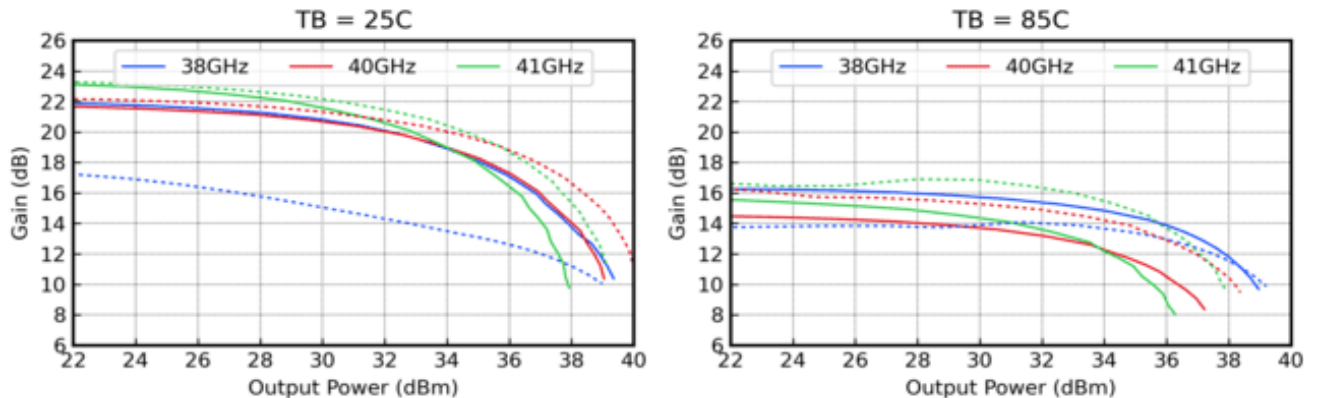
**NPR versus Output Power and Central Frequency**

**Test conditions :**  $I_{dq} = 310\text{mA}$ ,  $TB = 25^\circ/85^\circ\text{C}$ , solid line  $V_D = 20\text{V}$ , dashed line  $V_D = 25\text{V}$



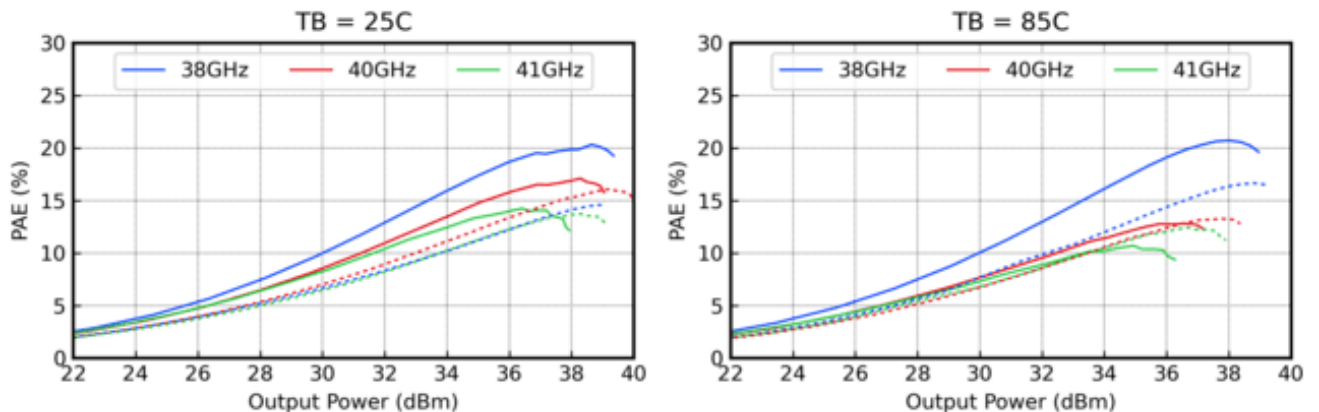
**Gain versus Output Power and Central Frequency**

**Test conditions :**  $I_{dq} = 310\text{mA}$ ,  $TB = 25^\circ/85^\circ\text{C}$ , solid line  $V_D = 20\text{V}$ , dashed line  $V_D = 25\text{V}$

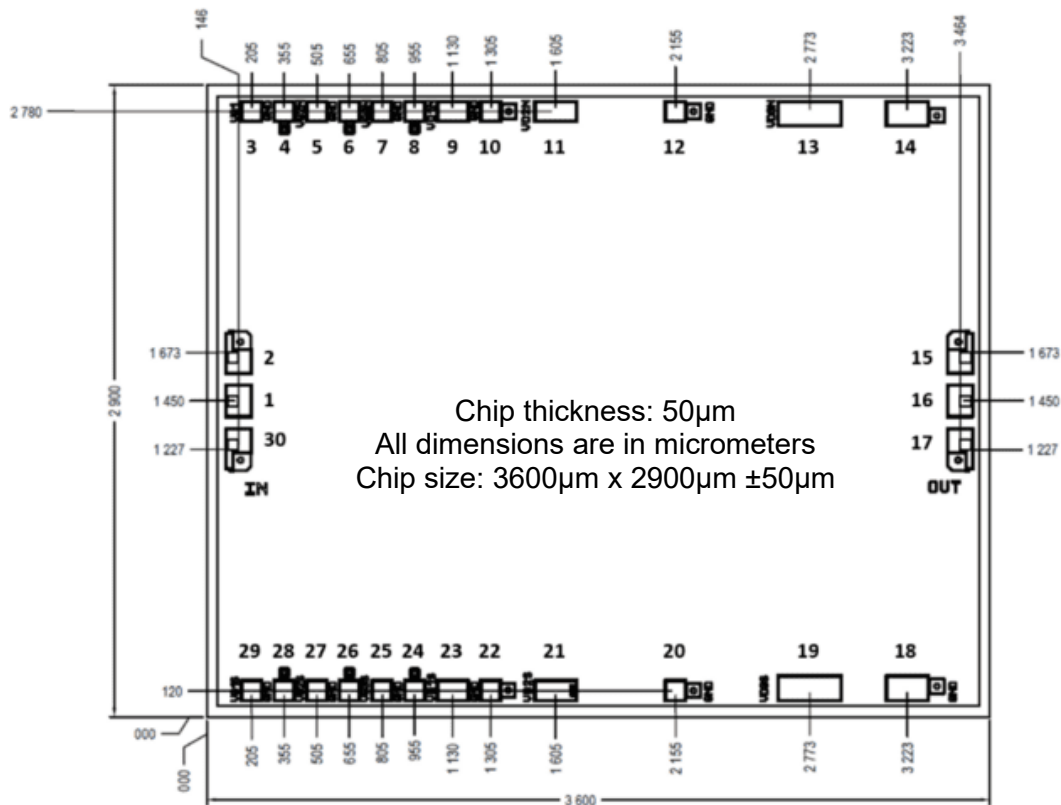


**PAE versus Output Power and Central Frequency**

**Test conditions :**  $I_{dq} = 310\text{mA}$ ,  $TB = 25^\circ/85^\circ\text{C}$ , solid line  $V_D = 20\text{V}$ , dashed line  $V_D = 25\text{V}$

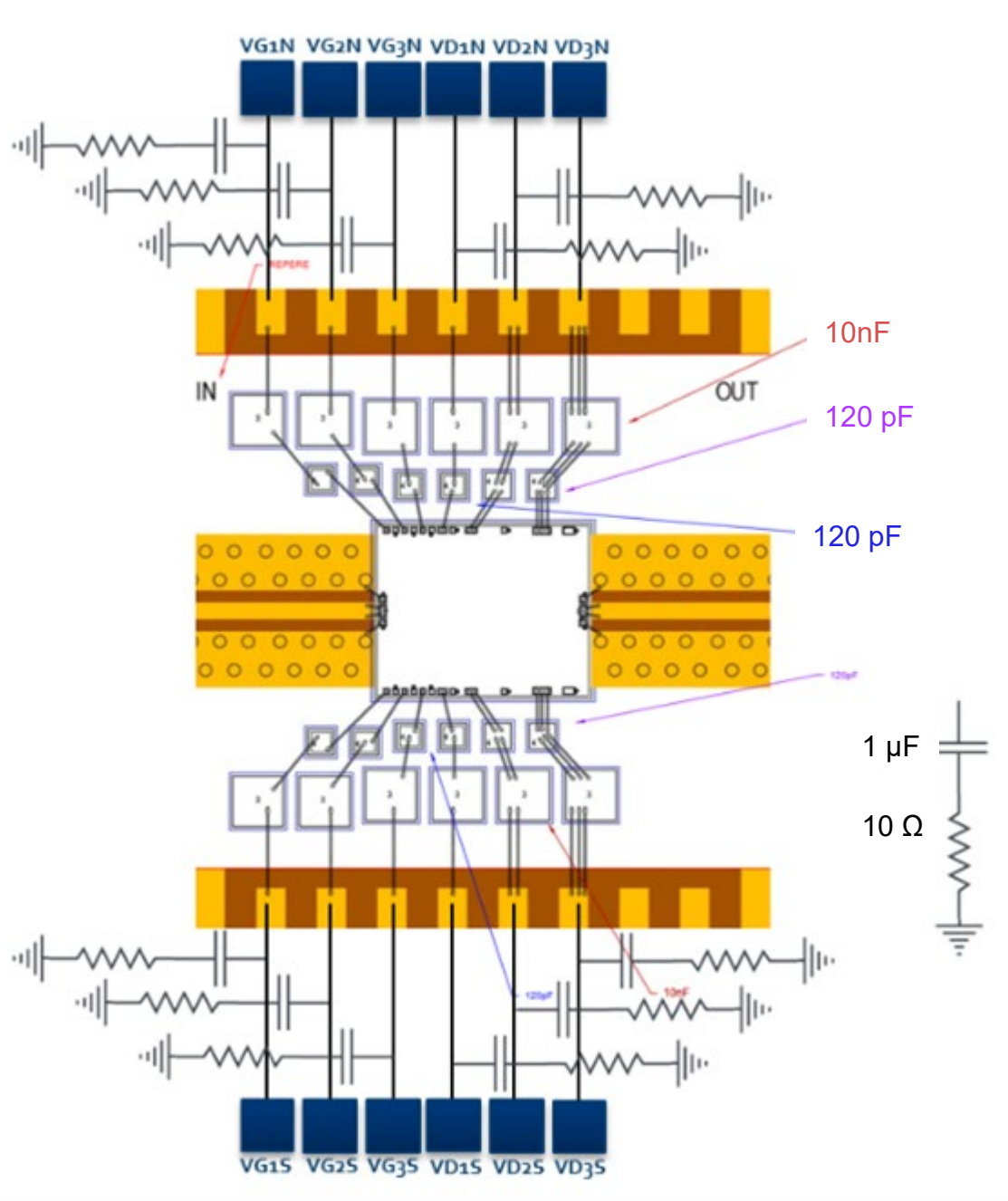


## Mechanical Data



PAD Number	Name	Description	Pad size
1	RF IN	Input RF port	118µm x 210µm
3	G12	DC Gaiter voltage, 1 <sup>st</sup> stage, North	96µm x 96µm
5	G3	DC Gate voltage 2 <sup>d</sup> stage, North	96µm x 96µm
7	G4	DC Gate voltage 3 <sup>d</sup> stage, North	96µm x 96µm
9	D12	DC Drain voltage, 1 <sup>st</sup> stage, North	196µm x 96µm
11	D3	DC Drain voltage 2 <sup>d</sup> stage, North	196µm x 96µm
13	D4	DC Drain voltage 3 <sup>d</sup> stage, North	296µm x 116µm
16	RF OUT	Output RF port	118 µm x 210 µm
19	D4	DC Drain voltage 3 <sup>d</sup> stage, South	296µm x 116µm
21	D3	DC Drain voltage 2 <sup>d</sup> stage, South	196µm x 96µm
23	D12	DC Drain voltage, 1 <sup>st</sup> stage, South	196µm x 96µm
25	G4	DC Gate voltage 3 <sup>d</sup> stage, South	96µm x 96µm
27	G3	DC Gate voltage 2 <sup>d</sup> stage, South	96µm x 96µm
29	G12	DC Gaiter voltage, 1 <sup>st</sup> stage, South	96µm x 96µm
2,4,6,8,10,12,14,15,17,18,20,22,24,26,28,30	GND	Ground	96µm x 96µm

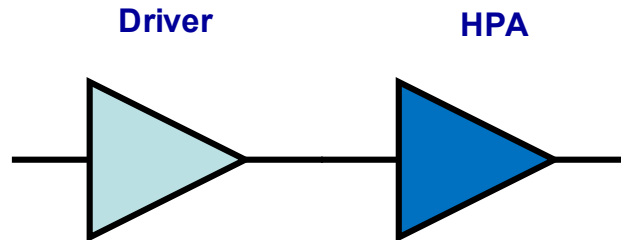
Recommended Assembly Plan



3 levels of decoupling capacitor have been used, 2 on the tab and 1 on the board. The first level is composed of 120 pF chip capacitors, the second level is composed of 10nF chip capacitors, the third level is composed of 1µF SMD 1210 capacitors with 10Ω series resistance. The first two levels should be as close as possible to the die.

## Recommended UMS Power chain

The CHA8454-99F is recommended with the CHA5659-98F as driver, with a total small signal gain above 45dB. For more information about the CHA5659-98F, see our website [www.ums-rf.com](http://www.ums-rf.com)



Reference	CHA5659-98F	CHA8454-99F
Frequency	36-44GHz	37.5-43.5GHz
Gain	22dB	24
Psat	30dBm <sup>(1)</sup>	40dBm
Drain Voltage	6V	20V
Quiescent Current	0.8A	0.56A

<sup>(1)</sup> Referring to the P1dB for the CHA5659-98F.

**Notes**

## ESD Sensitivity

Parameter	Classification	Standard
Human Body Model (HBM)	1A	ANSI/ESDA/JEDEC - JS-001

## Recommended reflow process assembly

Refer to the application note AN0001 available at <https://www.ums-rf.com> for die attach.

## Recommended environmental management

UMS products are compliant with the regulation in particular with the directives RoHS N°2011/65 and REACH N°1907/2006. More environmental data are available in the application note AN0019 also available at <https://www.ums-rf.com>.

## Recommended ESD management

Refer to the application note AN0020 available at <https://www.ums-rf.com> for ESD sensitivity and handling recommendations for the UMS products.

## Ordering Information

Chip form :

CHA8454-99F/00

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